| | Application No. | Applicant(s) | |
|---|---|--|-------------------------|
| Notice of Allowability | 10/603,629 | WINDLASS ET AL. | |
| | Examiner | Art Unit | ,/ |
| | Vikki H Trinh | 2814 | X |
| The MAILING DATE of this communication appearance All claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIOF the Office or upon petition by the applicant. See 37 CFR 1.313 | (OR REMAINS) CLOSED in or other appropriate comm IGHTS. This application is | n this application. If not included unication will be mailed in due c | d ourse. THIS |
| 1. X This communication is responsive to 10/24/04. | | | |
| 2. ⊠ The allowed claim(s) is/are <u>1-25</u> . | | | |
| 3. $igotimes$ The drawings filed on <u>06/24/03</u> are accepted by the Exami | ner. | | |
| 4. | | | |
| attached Examiner's comment regarding REQUIREMENT | FOR THE DEPOSIT OF BIO | OLOGICAL MATERIAL. | |
| Attachment(s) 1. Notice of References Cited (PTO-892) 2. Notice of Draftperson's Patent Drawing Review (PTO-948) 3. Information Disclosure Statements (PTO-1449 or PTO/SB/0 Paper No./Mail Date 4. Examiner's Comment Regarding Requirement for Deposit of Biological Material | 6. Interview S Paper No. 7. Examiner's | formal Patent Application (PTO ummary (PTO-413), /Mail Date Amendment/Comment Statement of Reasons for Allov | , |

Art Unit: 2814

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Allowable Subject Matter

- 1. Claims 1-25 are allowed.
- 2. The following is an examiner's statement of reasons for allowance: The prior art of record does not disclose either in singly or in combination a combination wafer or a microelectronic die having a substrate, a first set of alternating dielectric layers and layers of metal lines, a third set of alternating dielectric layers and layers of metal lines on the second set, the third set having a third guard ring trench therein, above the second guard ring trench and having a third width which is wider than the second width, a third guard ring layer formed on surfaces of the third guard ring trench, including partially on a top surface of the second guard ring layer where the second guard ring layer is formed on the top surface of the upper layer of the second set and partially on a top surface of an upper layer of the third set, and other elements in the claims.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

Any inquiry concerning this communication or earlier communications from the Examiner should be directed to Vikki Trinh whose telephone number is (571) 272-1719. The Examiner can normally be reached from Monday-Friday, 9:00 AM - 5:30 PM Eastern Time. If attempts to reach the examiner by telephone are unsuccessful, the Examiner's supervisor, Mr. Wael Fahmy, can be reached at (571) 272-1705. The office fax number is 703-872-9306.

Any request for information regarding to the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Also, status information for published applications may be obtained from either Private PAIR or Public Pair. In addition, status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. If you have questions pertaining to the Private PAIR system, please contact the Electronic Business Center (EBC) at 866-217-9197 (toll free).

Lastly, paper copies of cited U.S. patents and U.S. patent application publications will cease to be mailed to applicants with Office actions as of June 2004. Paper copies of foreign patents and non-patent literature will continue to be included with office actions. These cited U.S. patents and patent application publications are available for download via the Office's PAIR. As an alternate source, all U.S. patents and patent application publications are available on the USPTO web site (www.uspto.gov), from the Office of Public Records and from commercial sources. Applicants are referred to the Electronic Business Center (EBC) at http://www.uspto.gov/ebc/index.html or 1-866-217-9197 for information on this policy. Requests to restart a period for response due to a missing U.S. patent or patent application publications will not be granted.

Vikki Trinh, Patent Examiner AU 2814

> Howard Weiss Patent Examine